

«GreetingLine»

Did you know that Simbeor has the most comprehensive stackup planning capabilities to design predictable interconnects. It is easy to define PCB or packaging stackup structure in Simbeor environment and build broadband models for any type of PCB transmission line for a target impedance or pre-defined geometry: strip or microstrip, single-ended, edge-coupled and broad-side coupled differential, single-ended and differential coplanar waveguides and so on. Cross-sections with practically any number of traces can be easily simulated for crosstalk evaluation. To account for manufacturing defects, trace shape can be defined as trapezoidal, hat-shaped, butterfly or hexagonal. Broadband causal dielectric models such as multi-pole Debye, Wideband Debye (aka Djordjevic-Sarkar), multi-pole Havriliak-Negami as well as mixtures of dielectrics can be used to simulate the effects of dielectric polarization. To simulate effect of conductor roughness, six commonly used roughness models are available in form of the unified multi-level model defined with two parameters per one level. Impact of fiber-weave, meshed planes, guarded traces, via fences on the transmission line parameters can be simulated in Simbeor and accounted for in the final board design. Multiple stackups can be created within one Simbeor solution for comparative study.

Pre-layout signal integrity analysis is the most important step in the interconnect design flow and it starts with the stackup planning and exploration. The models at this step must be as accurate as possible – it can reduce or completely eliminate the need in excessive post-layout analysis and verification. **To ensure the analysis to measurement correlation, Simbeor is formally validated and supports systematic approach to the stackup planning step.** See what is important to know during the stackup exploration at “[Advanced stackup planning with the impedance, delay and loss validation](#)”.

Availability: Simbeor THz is available for customers and evaluation at [downloads section](#). Simbeor Qualify license can be used for all stackup planning activities with the quasi-static Simbeor SFS solver. Method of Lines 3DML solver can be used to simulate effects of single or periodic discontinuities (flexible interconnects) and high-frequency dispersion. It is included into Simbeor Explore license. Unique Trefftz Finite Element 3DTF solver can further extend stackup planning capabilities with the analysis of micron-size traces (High Bandwidth Memory interconnects). It is included in Simbeor Complete license. For more information on product pricing and availability or demo, contact Simberian at info@simberian.com.

Happy Summer Days!
Team Simberian

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